

Thermal Test Report

Model : YY-A202

Thermal Performance Contest

Date: Apr. 09, 2004

THIS TEST REPORT IS PROVIDED "AS IS" WITH NO WARRANTY WHATSOEVER, WHETHER EXPRESS, IMPLIED OR STATUTORY, INCLUDING BUT NOT LIMITED TO THOSE FOR NON-INFRINGEMENT OF INTELLECTUAL PROPERTY, MERCHANTABILITY OR SATISFACTORY QUALITY, FITNESS FOR ANY PARTICULAR PURPOSE, OR ANY WARRANTY OTHERWISE ARISING OUT OF ANY PROPOSAL, SPECIFICATION OR SAMPLE.

YEONG YANG ASSUMES NO RESPONSIBILITY FOR ANY ERRORS WHICH MAY APPEAR IN THIS DOCUMENT

Table of Contents

1) Introduction.....	1
2) References.....	1
3) Thermal Test	1
1. Test Configuration.....	2
2. <u>Test Equipment Used.....</u>	<u>2</u>
3. Test Process	2
4. Data Recorded.....	2
5. Thermal Test Results.....	3
4) Summary/Recommendations	3
<u>Table 4.1 & 4.2 (Test Result & Sample Picture)</u>	

1. Introduction

The purpose of this evaluation is to find the best performance thermal solution by system operated as for Intel P4 3.2G processor.

2. References

ATX spec <http://formfactors.org>

3. Thermal Test

3.1 Test Configuration

Chassis	YY-A202
Power Supply	Enhance ENP-2725H
Chassis Fan	TOP DF1206BH, Hi Speed: 4400RPM, Quantity:2 TOP DF1206BM, Middle Speed: 3700RPM, Quantity:2
Processor	Intel P4 Prescott FMB1.5 3.2GHz/800MHz, Quantity:1
Processor Thermal solution	Glacialtech Igloo 4360 Cooler Fan(8cm) Speed:2400 RPM,dBA:26
Motherboard	Model 1~8 :AUSU P4P800-VM Model 9~10 :GIGABYTE 8IPE1000MK
Memory	Kingston DDR400 512MB, Quantity: 2
Hard Drive	SEAGATE 40G, Quantity: 1
CD ROM	Cyber CD526D, Quantity: 1
Floppy Drive	Mitsumi D359M3, Quantity: 1
PCI :AGP Card	Albatron FX5200, Quantity: 1
PCI: Sound Card	ESS SC1938, Quantity: 1
PCI: Lan Card	D-LINK DFE-530TX, Quantity: 1

3.2 Test Equipment Used

FULL SYSTEM OPERATION

Fluke Hydra 2635A

Software: Intel P4 Prescott MAXPOWER (85% & 100%)

3.3 Test Process

The peripherals listed in section 1 were installed in the chassis and thermocouples were attached at the points designated in section 4. The chassis was tested in a controlled temperature held at a constant 35°C. The thermal readings communicated from the sensors on the test board to the test software. The system was exercised until the initial thermal gradient reached a consistent level with a slope-nearing zero. During testing, the ambient temperature was monitored approximately 2" from the front bezel of the chassis.

3.4 Data Recorded

Temperature readings are measured at the following location(s):

- Ambient -- Hotbox ambient temperature (2" from the front center of the chassis)
- Tinlet1 – Internal ambient temperature of the processor heatsink .5" away from the center of fan hub (near the rear port)
- Tinlet2 – Internal ambient temperature of the processor heatsink .5" away from the center of fan hub (near the PSU)

- Tinlet3 – Internal ambient temperature of the processor heatsink .5” away from the center of fan hub (near the DIMM slot)
- Tinlet4 – Internal ambient temperature of the processor heatsink .5” away from the center of fan hub (near the chipset)
- Tcase -- Processor case temperature

- **Test Result** (see table 4.1), & Test mode details (Table 4.2)

- **Summary:** *PASS*

In the conditions of the system must build two pieces of system fans in hi-speed; in the meanwhile to compliant with CAG1.1 design.

- The tests intends to understand what different from the test results between run trace software 85% level and 100%, and disconnect PCI card and connect 3 x 8w PCI card?.
To compare the test result of mode 1,2 and 3,4. We found the chassis do provide a good ambient (Tambient) with its thermal performance however on 85% or 100%.
- The tests intends to understand how thermal solution improved if the chassis have engineering changes to meet CAG design guide rev.1.1?
To compare the test result of mode 4 and mode 6. We found the chassis meets CAG design guide rev.1.0 may not meet Ta38°C . It shown the CAG rev.1.1 design guide provided thermal advantages.
- The tests intends to understand what different if we installed difference fan speed of system fans? Some customers maybe care the acoustic issues.
To compare the test result of mode 4 and mode 8. We found the chassis built low speed system fan (mode 8) may not meet Ta38°C .
- The test s intends to understand how is the result in the **worse case of normal operation?** we try to test it in ambient **30°C**.
We may try to compare the test result of mode 4 and mode 5. It certainly meet Ta38°C , so we suggest customer may keep use low-speed fans to have better acoustic result in the friendly operation.
- The test s intends to understand what impact to processor power and thermal result if just change another motherboard?.
To compare the test result of mode 3,4 and mode 9,10. Both meet Ta38°C , and Tambient, Tcase....all measured values got changed, it shown the different system may deliver different thermal profile.

Yeong Yang Technology, Engineering Validation

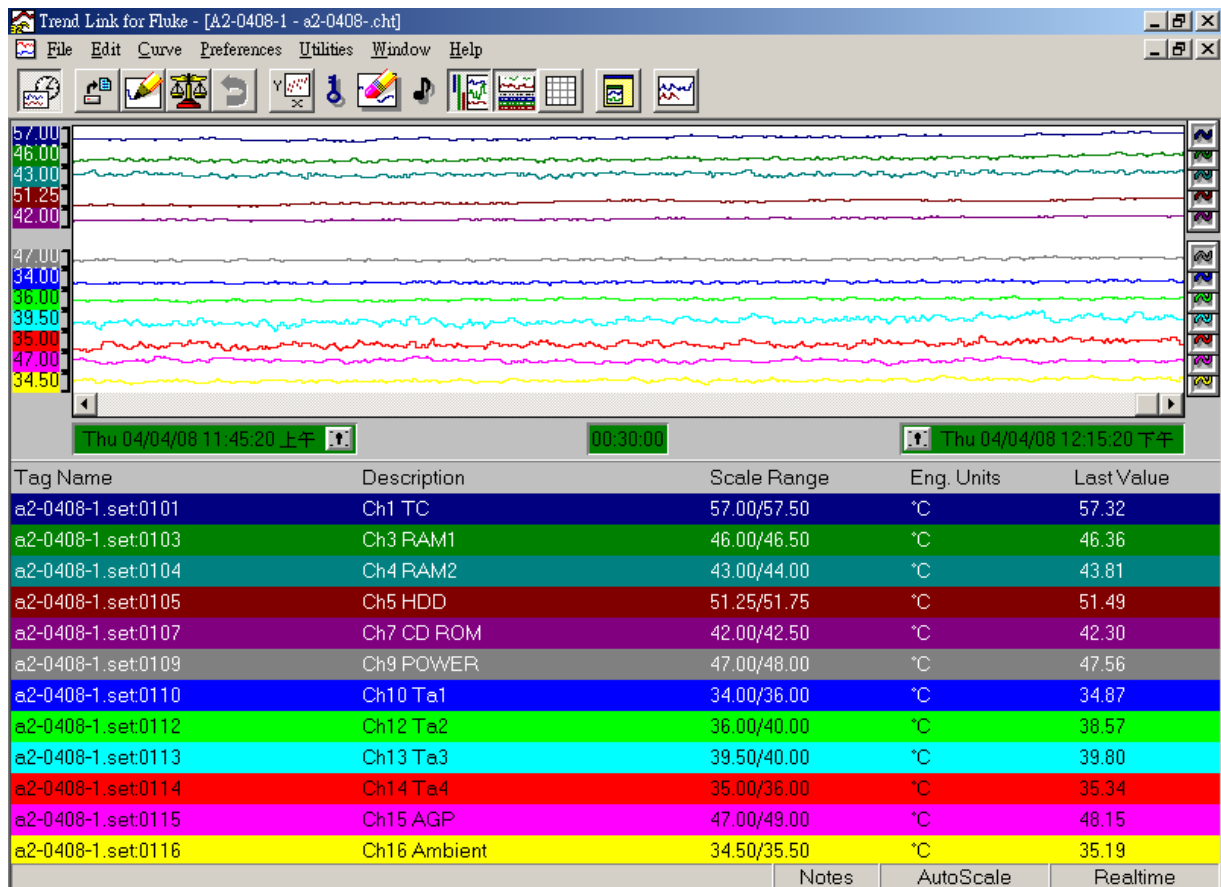
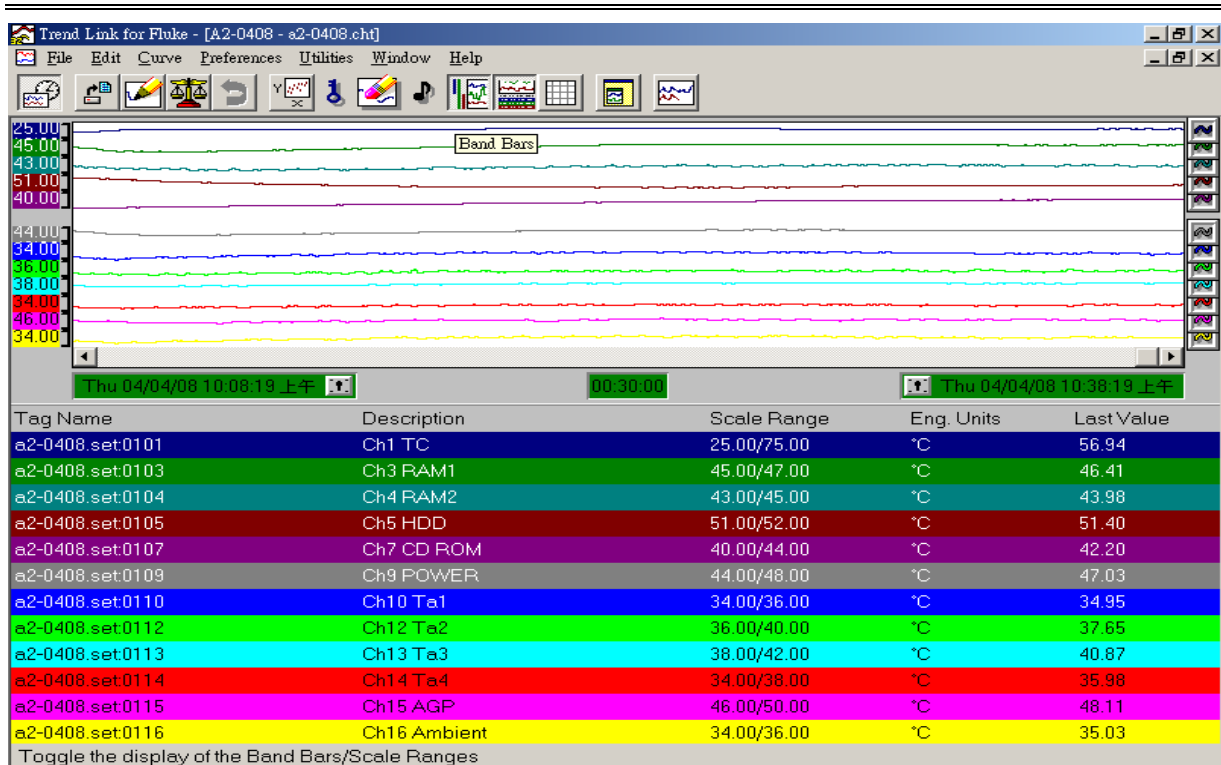
Table 4.1
Date: Apr. 09, 2004

Position	Mode 1	Mode 2	Mode 3	Mode 4	Mode 5	Mode 6
Panel	02	02	02	02	02	02(A2CN)
Power Model	Enhance ENP-2725H (with 8cm Fan for airflow in, vents for air flow out)					
System Fan (Mounted in rear side of chassis)	TOP DF1206BH					
Airguide (CAG1.1)	Yes	Yes	Yes	Yes	Yes	CAG1.0
PCI Card Install	Disconnect	Disconnect	Yes	Yes	Yes	Yes
Run the test under the software on 85% or 100% level	85%	100%	85%	100%	100%	100%
DIMM-1	46.4	46.4	46.4	46.6	41.8	46
DIMM-2	44	43.8	43.6	44.1	39.1	45.2
HDD	51.4	51.5	51.3	51.5	45.9	49.3
CD ROM	42.2	42.3	42.3	42.4	37.3	40.2
POWER	47	47.6	47.1	47.5	42.8	48.6
AGP	48.1	48.2	50.3	51	46.3	45.9
T-inlet 1	35	34.9	34.9	35.1	29.7	38.3
T-inlet 2	37.7	38.6	37.6	40.1	32.8	41.4
T-inlet 3	40.9	39.8	40.1	39.4	34.2	39.4
T-inlet 4	36	35.3	35.6	35.5	30.5	35.5
T-inlets average Tambient(1~4)	37.4	37.2	37.1	37.5	31.8	38.7
T-case	56.9	57.3	56.9	57.4	53.7	59
Ambient(case outside)	35	35.2	35.1	35.1	30.1	35

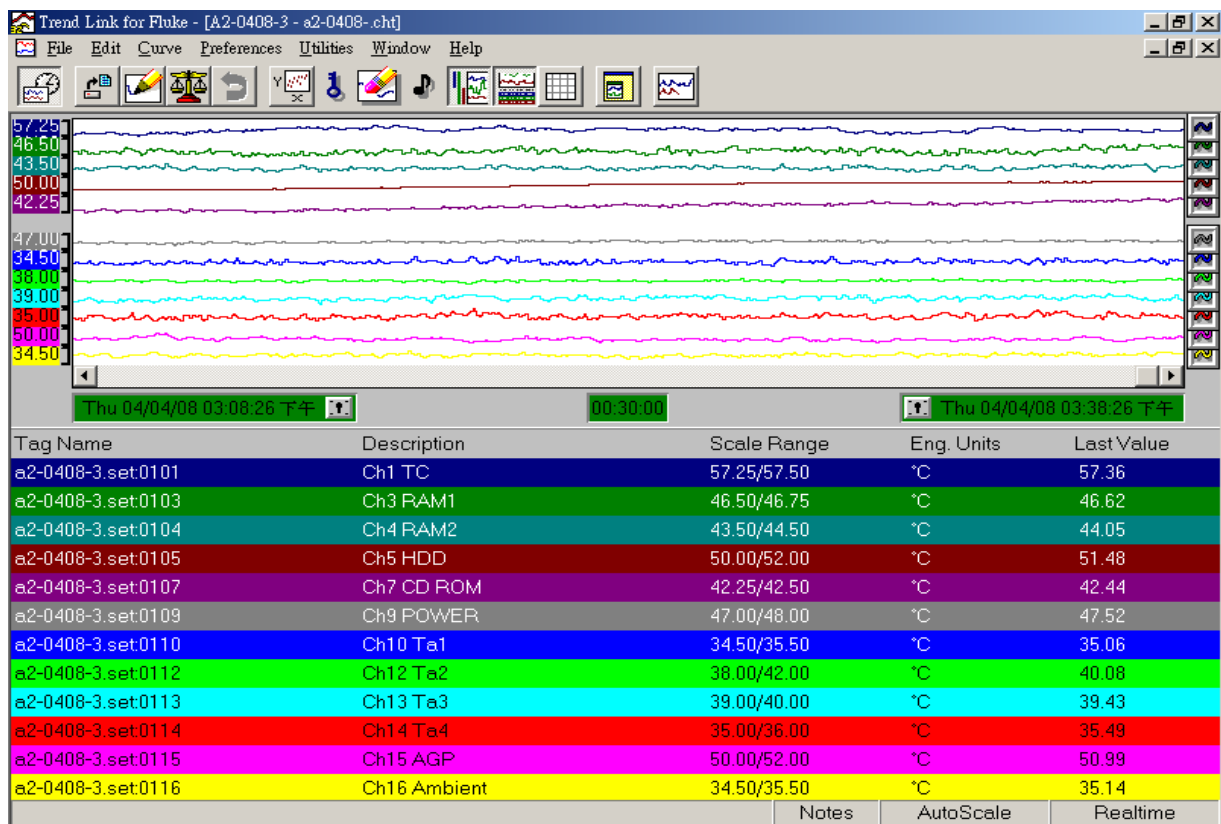
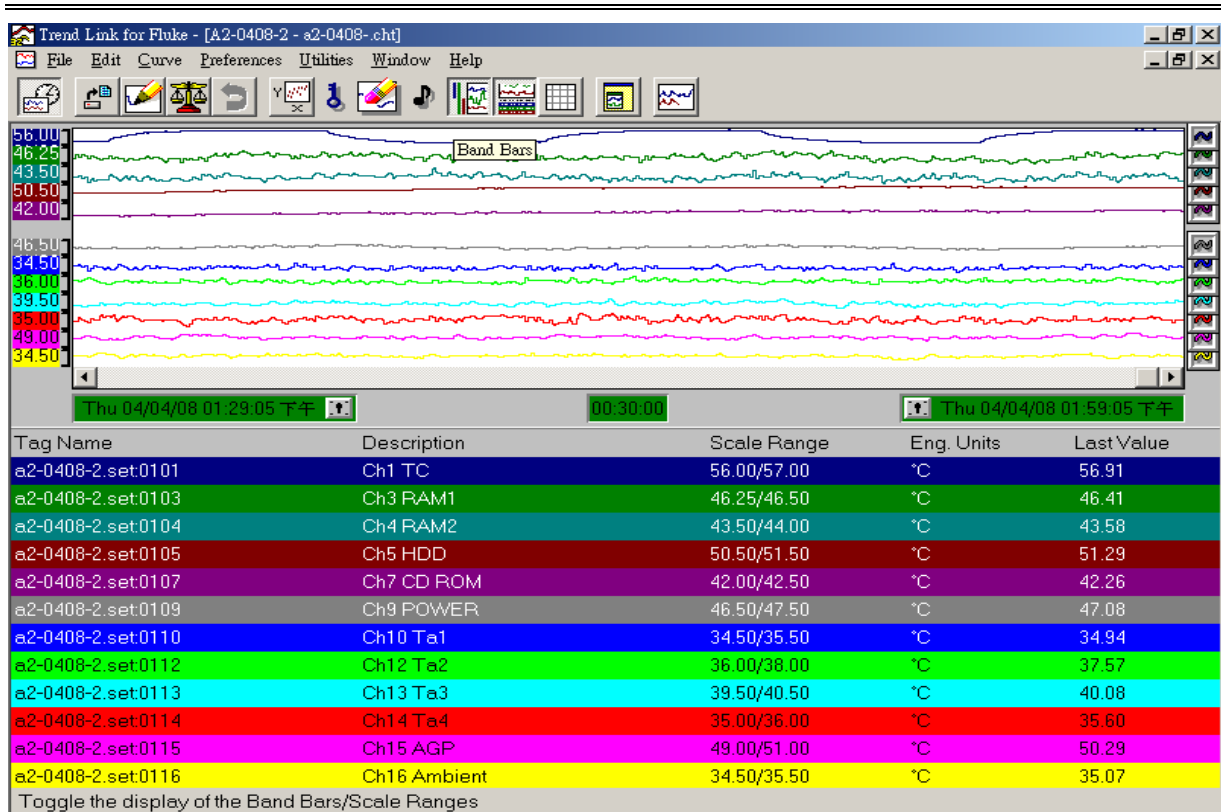
Yeong Yang Technology, Engineering Validation

Position	Mode 7	Mode 8	Mode 9	Mode 10
Panel	06	02	02	02
Power Model	Enhance ENP-2725H (with 8cm Fan for airflow in, vents for air flow out)			
Fan Model	TOP DF1206BH	TOP DF1206BM	TOP DF1206BH	
Airguide (CAG1.1)	Yes	Yes	Yes	Yes
PCI Card Install	Yes	Yes	Yes	Yes
Run the test under the software on 85% or 100% level	100%	100%	85%	100%
DIMM-1	46.9	49.7	49.2	49.1
DIMM-2	44.2	46.2	44.9	44.7
HDD	52.1	53.8	50.8	51.4
CD ROM	42.5	45.1	41.1	41.1
POWER	47.8	49	46.1	46.6
AGP	50.7	63.2	50.9	50.9
T-inlet 1	35.3	37.7	34.7	34.4
T-inlet 2	38.2	41.6	37.6	37.3
T-inlet 3	41.2	41.9	40.4	40.3
T-inlet 4	36.4	37.5	35.3	34.6
T-inlets average Tambient(1~4)	37.8	39.7	37	36.7
T-case	57.9	59.6	55.6	56.3
Ambient(case outside)	35.1	35.1	35.1	35

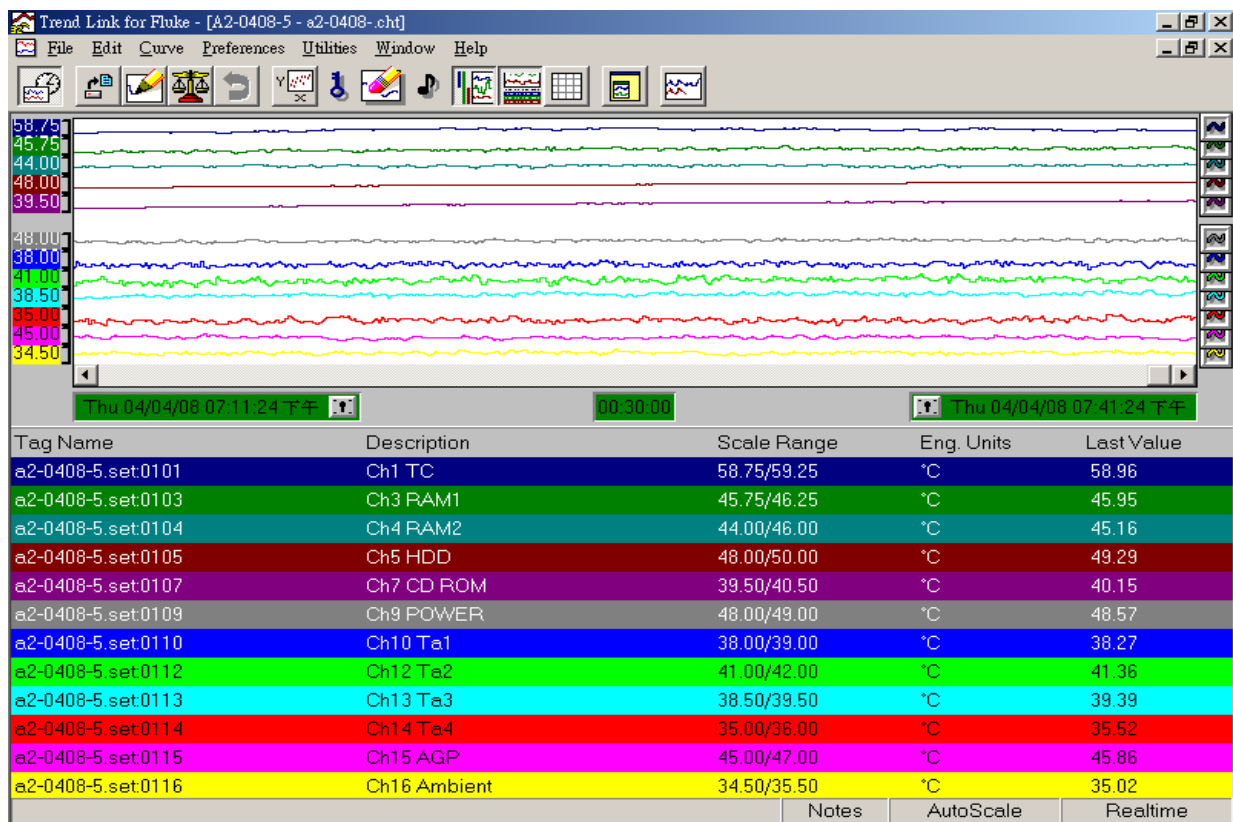
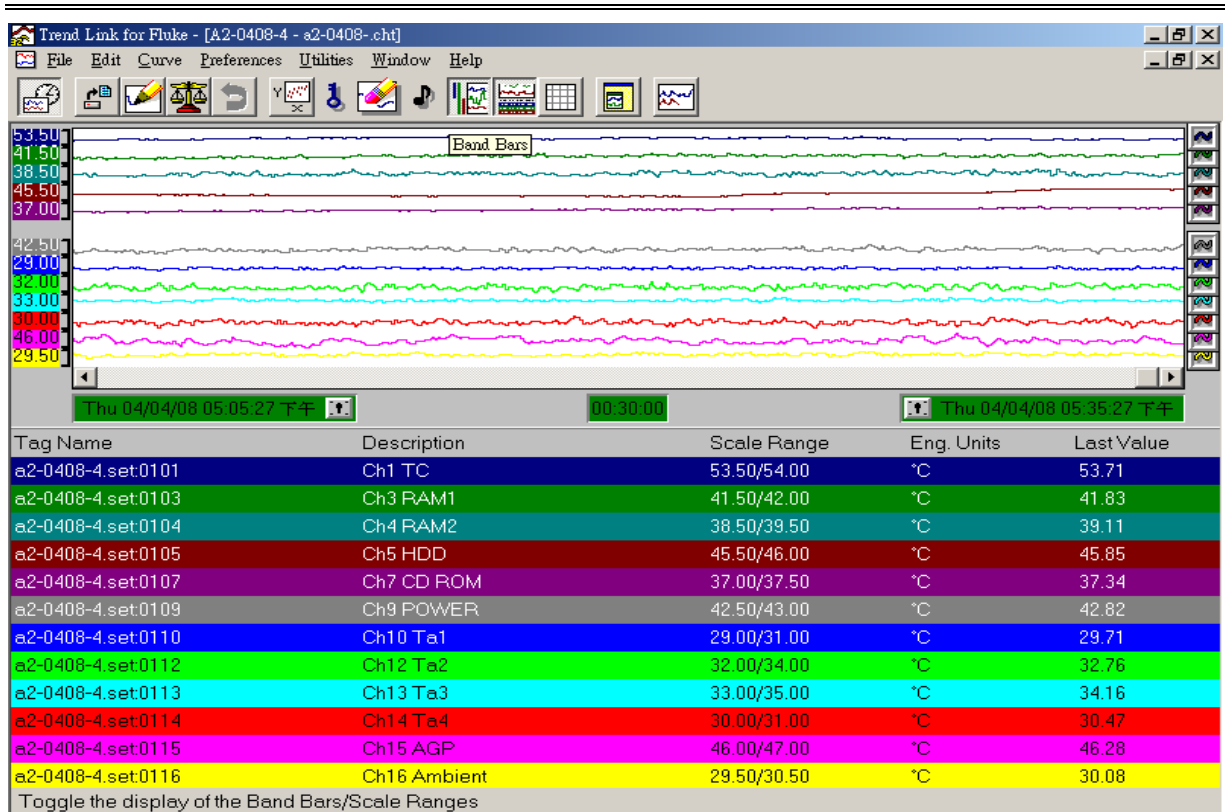
Yeong Yang Technology, Engineering Validation



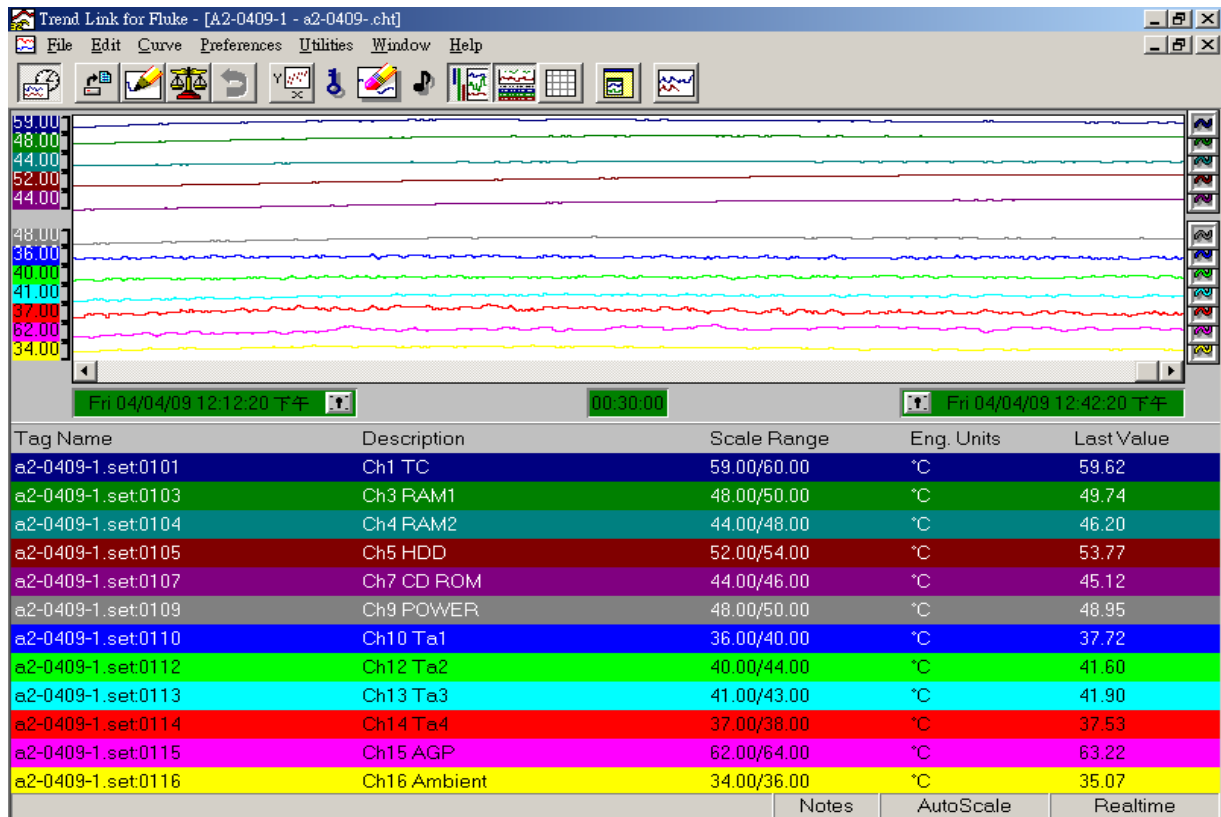
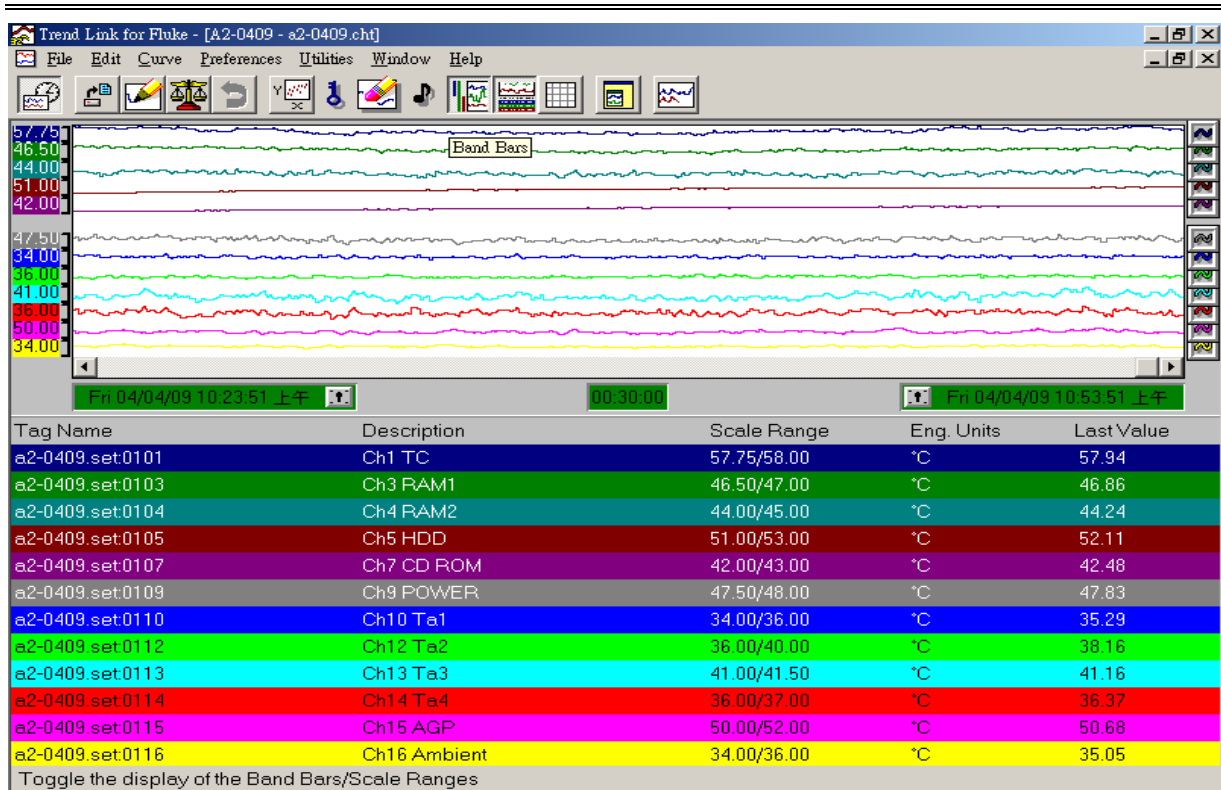
Yeong Yang Technology, Engineering Validation



Yeong Yang Technology, Engineering Validation



Yeong Yang Technology, Engineering Validation



Yeong Yang Technology, Engineering Validation

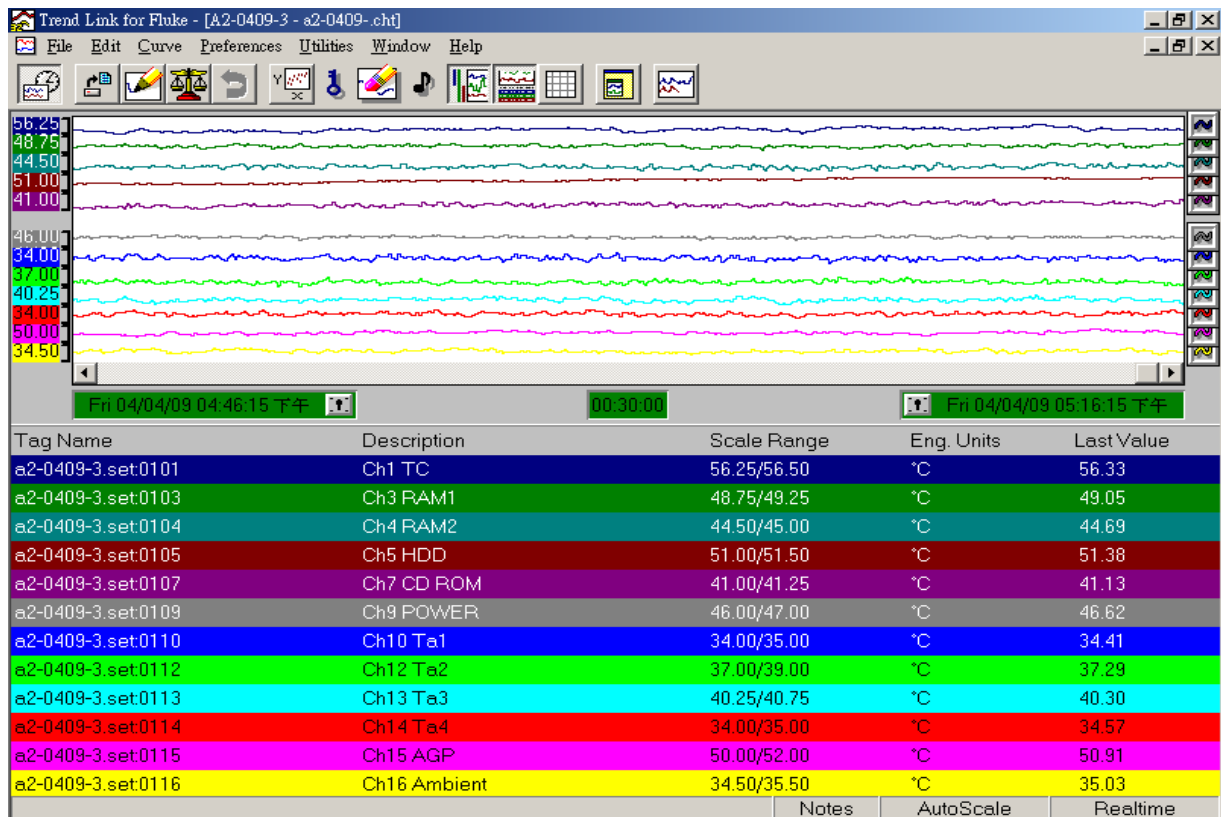
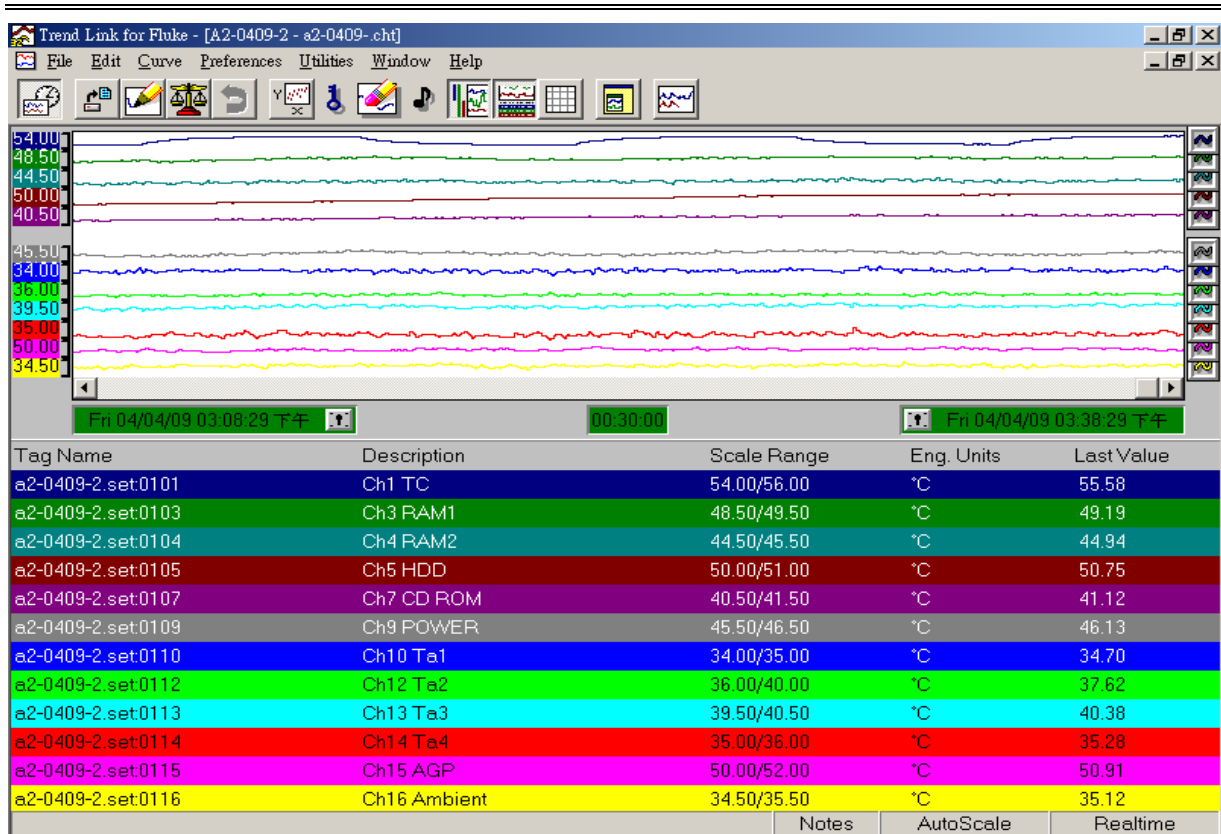


Table 4.2



The view of the chassis front side.



The view of the chassis left side.



The view of the chassis right side.



The view of the chassis back side.



The view of thermocouples connections.

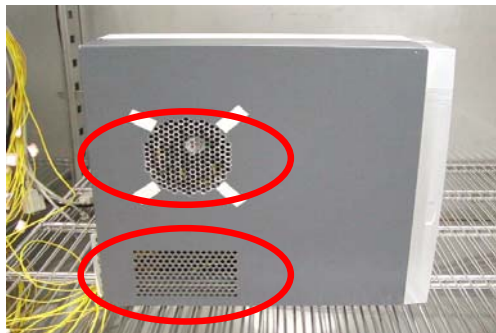


The view of CAG 1.1 (the diameter of guide is enlarged)
The tested unit is a Prototype



The view of CPU Vents - before Engineering Change for CAG1.1. Called CAG1.0, i.e. the design meets CAG design guide rev.1.0

In this test, we used a modified side cover which some with some vents on PCI area that got the same concept as CAG1.1.



The view of CPU Vents & PCI Vents, meet CAG 1.1 (bigger Air Guide venting area and add vents for AGP, PCI area)